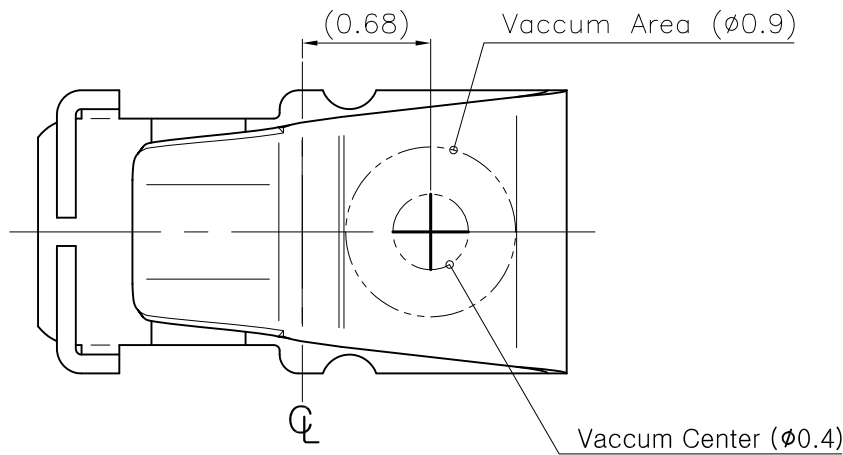
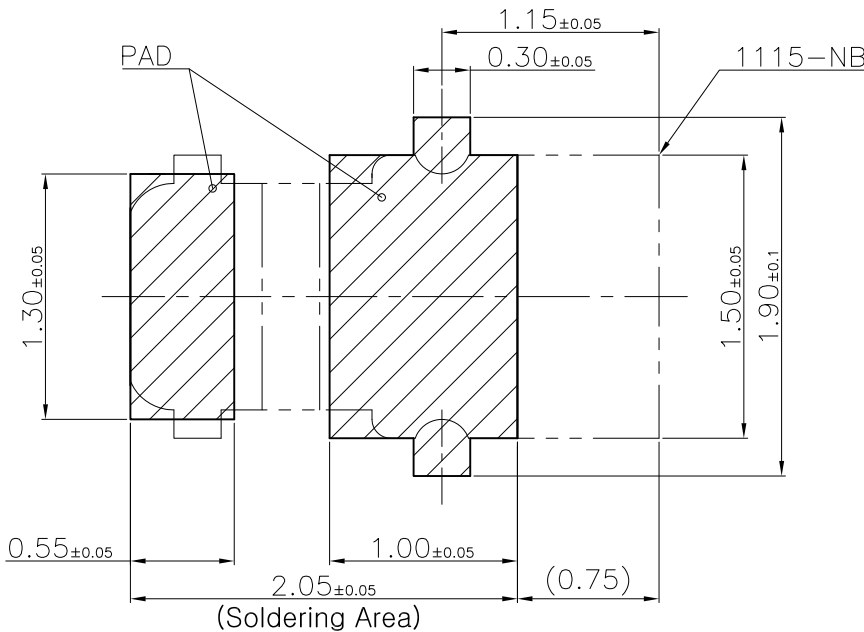
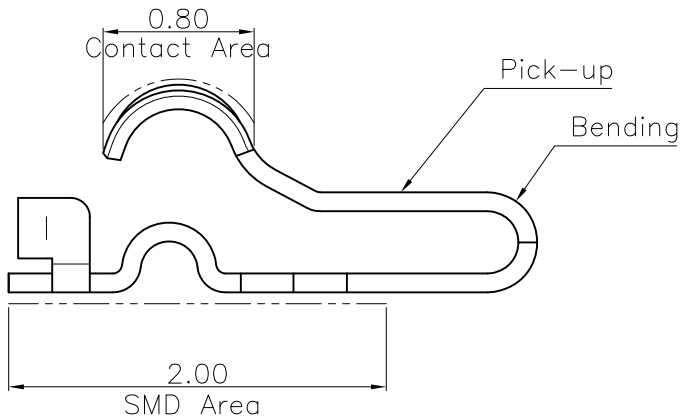
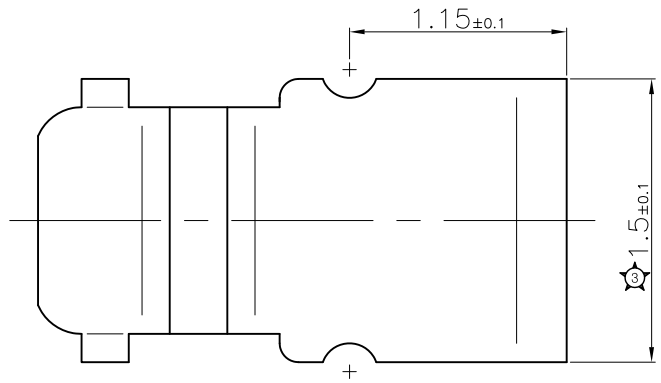
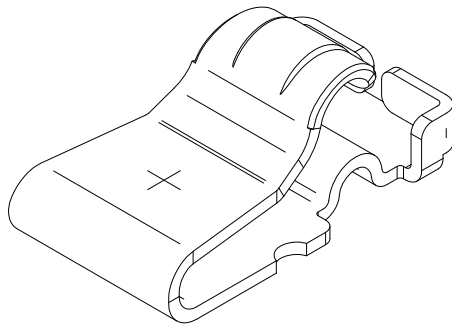
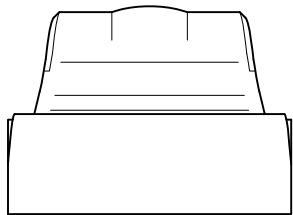
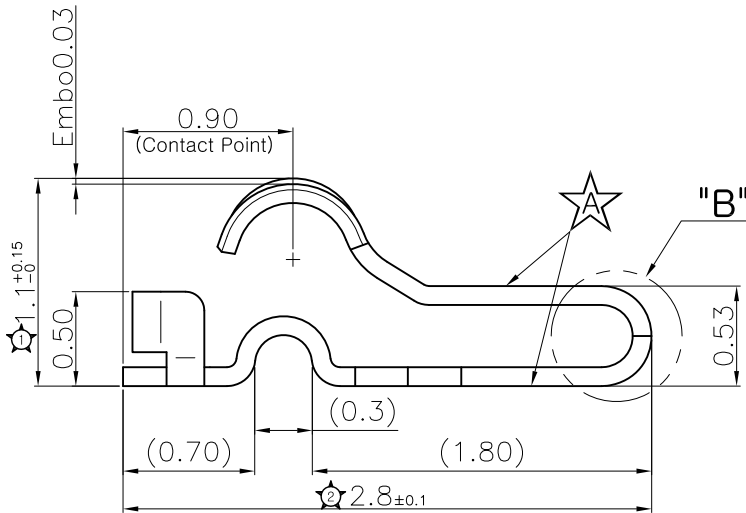


SIMULATION



RECOMMNEDED PCB LAYOUT(Top View)



PLATING AREA

- *NOTE
1. PLATING
 - Contact Area : Au 0.1μm Min over Ni 1.5~4.0μm.
 - SMD Area : Au 0.05 μm Min over Ni 1.50~4.0μm.
 - Bending & Pick-up : Ni 1.5~3.5μm.
 2. ☆ : C.T.Q
 3. ☆ : 평탄도 0.05 Max.
 4. Contact 가동거리(Max)는 0.6mm 이상으로 한다.
 5. Contact 가동거리 : 0.6mm
권장 Contact 높이 : 가동거리의 60~80% 범위 내
(0.36~0.48mm) => (0.62~0.74mm)
 6. 제품의 안정적 Contact을 위하여 Bending部 "B" 주위에 기구적인 간섭이 없을 것.
 7. 일반 공차 ±0.1 적용 할 것.

1	Contact	Ti-Cu			Note.1		t0.1	
No	Descriptions	Material			Finish		Remarks	
General Tolerance		Scale	N/S	Units	mm	Sheet	HJ-1115-NB ANTENNA CONTACT	
Dimension	mm (°)	Date	2013. 07. 05		1 of 1			
X	± 0.2	Drawn	Design	Checked	Reviewed	Approved	Customer Drawing	
X.X	± 0.1							
X.XX	± 0.05	J.S. Kim 2013/07/09		-	Y.J. Park 2013/07/09	S.K. Hong 2013/07/09	Rev. 0	
X.XXX	± 0.01	 HYUPJIN CONNECTOR						
ANGLE	± 1°	DWG No.					HJ-1115-NB-A1	